



- Custom Designed Molds and Tooling
- New and Refurbished
- Precision Machining
- Contract Thermoset and Thermoplastic Molding Services



- micro SAW
- Meta Grinder
- EMI Shield Equipment
- Flip Chip Bonder
- TC Bonder
- Vision Placement Systems
- Laser Marking and Cutting
- 3D Vision Inspection



- Dicing Blades
- Capillary Bonding Tools and Accessories



- Automatic and Semi-Automatic Die Attach Systems
- Programmable Systems
- Eutectic, Epoxy, Thermo-Compression, Thermo-Sonic
- Pick & Place, Flip Chip, Multi-Chip-Modules
- Waffle/Gel Packs, 300 mm Wafer



- Equipment for semiconductor and photovoltaic industries
- Vacuum Soldering Systems



- Test Handlers
- Test/Mark/Tape Machines
- Sorting Machines
- Pick & Place Machines
- Assembly Equipment & Tooling



- Package Development
- Film Assist Molding Technology and Systems
- Silver Sintering Systems
- Through Polymer Via (TPV) Technology



- Wedge-wedge and ball-wedge bonding on the same machine
- Bonding Types: Tab, Stitch, Ribbon, Bumping, Ball bonding, Coining, Security bonds
- Large 6" x 6" bonding area
- 90-degree deep access wedge bonding with 12.5 mm 'Z' axis travel
- Variety of wires: Gold, Copper (Wedge, Ball), Aluminum, Ribbon (Au or Al) for Wedge



- RF Preheaters



- Wafer Frames/Cassettes



- Trim/Form/Singulation Systems
- Specializing in Power Module Trim & Form
- Rapid Prototyping & Leadframe Design Support



- Dry Film Resist Lamination
- Wafer Mounters
- De-Taping Systems
- UV Irradiation Equipment



- Top or Bottom Transfer Molding Presses
- 12, 30, 50, 120, 250, 300 Clamp Tonnage Available
- Computer Controlled Closed-loop Transfer Profile



- Gravity Feed Test Handler (Tri-temp)
- Laser Marking System
- Manual Wire Bond Inspection Systems
- Customized Automation Solutions
- XYZ Module

For More Information:

Neu Dynamics Corporation • NDC International

110 Steamwhistle Drive • Ivyland, PA 18974 • 215-355-2460 • Fax: 215-355-7365

www.neudynamics.com • www.ndc-int.com • Sales@neudynamics.com